



12-20-01

2811

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

11/President
P. Walker
1-17-02

Inventor(s): Tae Heon LEE et al.

U.S. Serial No.: 09/687,048

U.S. Filing Date: October 13, 2000

Art Unit: 2811

Priority Claim: KR 99-44650

Priority Date: October 15, 1999

Title of Invention: LEADFRAME AND SEMICONDUCTOR
PACKAGE WITH IMPROVED SOLDER JOINT
STRENGTH

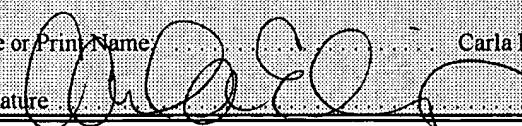
Attorney Reference: 45475-00026

99-44650

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PRELIMINARY AMENDMENT
WITH REPLACEMENT SECTION UNDER RULE 1.121(b)

Applicants respectfully request the Examiner to consider the following amendment and comments.